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Dated: May 2, 2006

Signature:

*Richard H. Anderson*  
(Richard H. Anderson)

Docket No.: 27702/10065  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Gary Wentworth et al.

Application No.: 10/706,196

Confirmation No.: 5990

Filed: November 12, 2003

Art Unit: 1614

For: ADHESION PROMOTERS FOR CORD-  
REINFORCED THERMOPLASTIC  
POLYMERIC MATERIALS AND  
SUBSTRATE/THERMOPLASTIC  
POLYMERIC MATERIAL COMPOSITES

Examiner: S. K. Poulos

**AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION**

MS Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

In response to the Office Action dated February 17, 2006, please amend the above-identified U.S. patent application as follows:

**Amendments to the Abstract** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 3 of this paper.

**Remarks/Arguments** begin on page 24 of this paper.